



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

\*: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	27/06/2014
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Arcidiacono Salvatore	<b>Representative Title</b>	IPG IPC Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VIPER25LDTR	KMQ7*MV58BE6	A	Z7GA	27/06/2014
Amount	UoM	Unit type	ST ECOPACK Grade	
150.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	9.9 X 3.9 X 1.25	16	gull wing	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KMQ7*MV58BE6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	4.099	mg	supplier	die	Silicon (Si)	7440-21-3		4.019	mg	980483	26793
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.01	mg	2440	67
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.008	mg	1952	53
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	488	13
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.017	mg	4147	113
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.006	mg	1464	40
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.002	mg	488	13
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	488	13
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1464	40
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.027	mg	6587	180
Leadframe	Copper & its alloys	64.749	mg	supplier	alloy	Copper (Cu)	7440-50-8		62.862	mg	970857	419080
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		1.479	mg	22842	9860
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.089	mg	1375	593
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.077	mg	1189	513
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.222	mg	3429	1480
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.014	mg	216	93
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.006	mg	93	40
Die attach	Other inorganic materials	0.776	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.637	mg	820876	4247
Die attach				supplier	glue or tape	Acrylate resins	Proprietary		0.093	mg	119845	620
Die attach				supplier	glue or tape	Heterocyclic organic compound	Proprietary		0.023	mg	29639	153
Die attach				supplier	glue or tape	Treated silica	Proprietary		0.023	mg	29639	153
Bonding wire	Precious metals	0.165	mg	supplier	wire	Gold (Au)	7440-57-5		0.165	mg	1000000	1100
encapsulation	Other Organic Materials	80.211	mg	supplier	mold compound	Silica, vitreous	60676-86-0		71.147	mg	886998	474313
encapsulation				supplier	mold compound	epoxy resin	Proprietary		6.417	mg	80001	42780
encapsulation				supplier	mold compound	Phenol resin	Proprietary		2.407	mg	30008	16047
encapsulation				supplier	mold compound	carbon black	0		0.24	mg	2992	1600